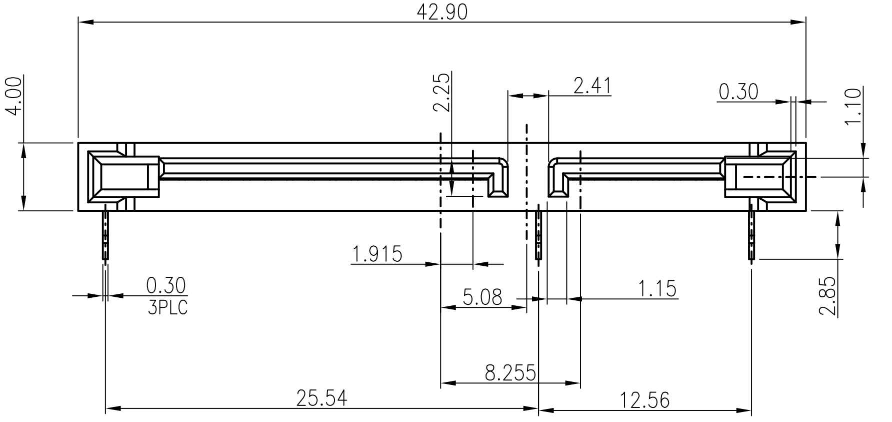
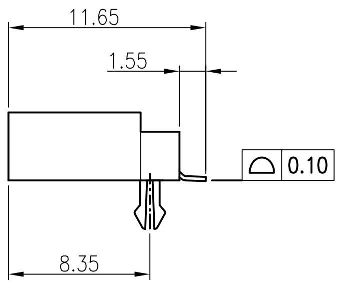
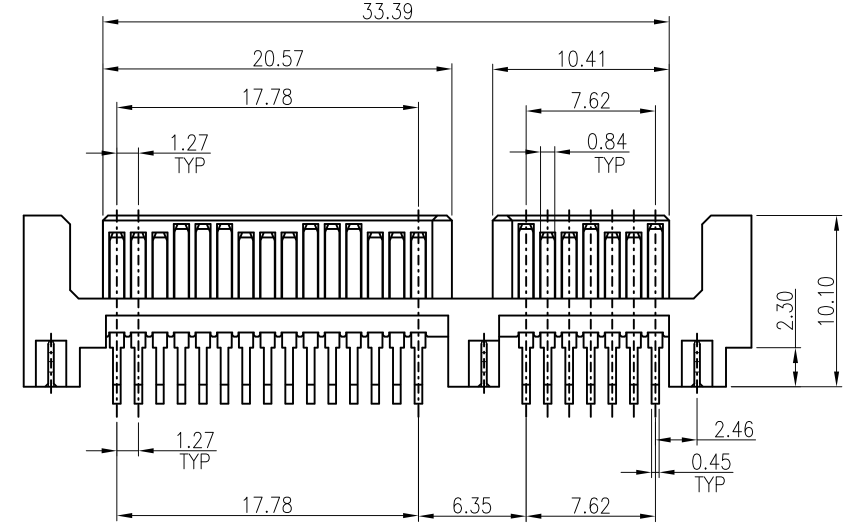




NOTES:
1.MATERIAL:
HOUSING:LCP 30% G/F UL94 V-0, COLOR:BLACK
CONTACT:PHOSPHOR BRONZE C5191H T=0.25mm
BOARD LOCK:BRASS C2680H T=0.30mm
2.FINISH:
CONTACT:GOLD FALSH/TIN PLATING ON CONTACT AREA
100u" MIN.TIN PLATING ON SOLDERTAILS
50u" MIN.NICKEL UNDERPLATING OVER ALL
BOARD LOCK:100u"MIN.TIN PLATION ON SOLDERTAILS
50u"MIN.TIN NICKEL UNDERPLATING OVER ALL



Ordering Information

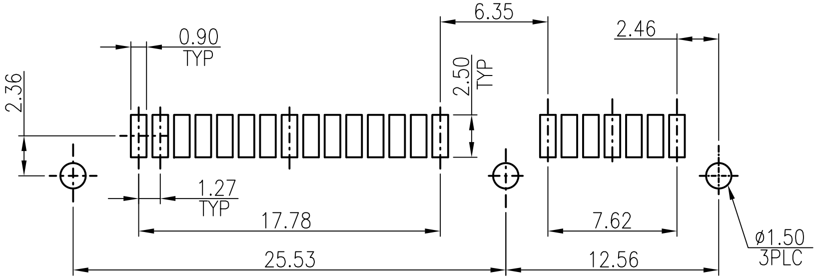
SA022M - XX 1864 B X - 47

Contact Area Plating
G1 : Gold Flash
G2 : 05 u"
G3 : 10 u"
G4 : 15 u"
G5 : 30 u"
G6 : 1u"
G7: 3u"
G8: 2u"

B=Boardlock
P=Post
G=Peg
W=wo B/P/G
C=Solder type
F=Press Fit
M=Solder type+ Press Fit
S=Sunk
L=Clamp

1=Tube
2=Tray
3=T&R+CAP
4=T&R+Mylar

RoHS
Compliant



P C B Layout
PCB TOLERANCE:±0.05

REV.	REVISION RECORD	DATE
A	Orignal	06/10/09'
B	Revised P/N	01/09/15'

General Tolerances
LINEAR 0.0 ±0.35
0.00±0.20
ANGLES ±3°
UNIT: mm(in)

A4	NAME	DATE
APPROVED	SUNNY	
DESIGNER	TED	
DRAWN	WING	

ARIBA
TECHNOLOGY CO., LTD.

TITLE: SATA 22P M SMT RA w 3 boardlock

DWG.NO.: SA22M-XX1864BX-47 | REV. B

SCALE 1 : 1 | SHEET 1 OF 1